

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. . . . . 08/940,685  
Filing Date . . . . . September 30, 1997  
Inventor . . . . . Batz et al.  
Assignee . . . . . Semitool, Inc.  
Group Art Unit . . . . . Unknown  
Examiner . . . . . Unknown  
Attorney's Docket No. . . . . SE10-0125  
Title: Methods For Plating Semiconductor Workpieces Using A Workpiece-Engaging  
Electrode Assembly With Sealing Boot

DECLARATION FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated  
below next to my name.

I believe I am an original, first and joint inventor of the subject  
matter which is claimed and for which a patent is sought on the  
invention entitled Methods For Plating Semiconductor Workpieces Using  
A Workpiece-Engaging Electrode Assembly With Sealing Boot, the  
specification of which was filed on September 30, 1997 as United States  
Patent Application Serial Number 08/940,685.

I hereby state that I have reviewed and understand the contents  
of the above-identified specification, including the claims, as amended by  
any amendment referred to above.

I acknowledge the duty to disclose information which is material  
to patentability as defined in 37 CFR §1.56.

I hereby claim foreign priority benefits under 35 U.S.C. §119(a)-(d)  
or §365(b) of any foreign application(s) for patent or inventor's  
certificate, or §365(a) of any PCT International application which

1 designated at least one country other than the United States, listed  
2 below and have also identified below, any foreign application for patent  
3 or inventor's certificate, or PCT International application having a filing  
4 date before that of the application on which priority is claimed:

5 . Application Number: Not applicable.

6 Country: Not applicable.

7 Filing date: Not applicable.

8 I hereby declare that all statements made herein of my own  
9 knowledge are true and that all statements made on information and  
10 belief are believed to be true; and further that these statements were  
11 made with the knowledge that willful false statements and the like so  
12 made are punishable by fine or imprisonment, or both, under  
13 Section 1001 of Title 18 of the United States Code and that such willful  
14 false statements may jeopardize the validity of the application or any  
15 patent issued thereon.

16 \* \* \* \* \*

17 Full name of inventor: Robert W. Batz, Jr.

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